IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under be international and Pan-American copyright conventions.			nder both lev	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	ials and Mfg Information			
Supplier	Information														
Company name*				npany unique ID			Unique ID Authority					Response Date*			
nsemi												2024-09-20			
Contact Na	ame	Title - Contact			P	Phone - Contact*				Email - Contact*					
Product-E	Inv-Stewards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
uthorized	l Representative*	Title - Representative			P	Phone - Representative*				Email - Representative*					
Product-E	Inv-Stewards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Iter		n Number Mfr Item Name]	Effective Date	Versio	Version Manufacturing Site		V	Weight*	UOM	Unit Type	
		NTLUS3C18PZTAG PFET UDFN 12V		7A 24MOHM	2024-09-20						4	.71	mg	Each	
Ianufac	cturing Proccess Informa	ntion													·
	erminal Plating / Grid Array Material		Terminal Base Alloy J-STD-0		-STD-020 MSL R	ating	Peak Process Body Temperatu		re Max Time at Peak Temperature		ure Num	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		CU Alloy 1			260 C		C	30 seco		second	ds 3				
omments															
vel 1 - ma	aximum time at peak temperat	ure during sol	ldering is 10-3	0 seconds											
or more i	nformation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.21 mg		Supplier	Silicon (Si)	7440-21-3		0.21	mg
Die Attach	0.13	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.026	mg
			Supplier	Silver (Ag)	7440-22-4		0.104	mg
Lead Frame	2.2	mg	Supplier	Silver (Ag)	7440-22-4		0.044	mg
			Supplier	Tin (Sn)	7440-31-5		0.0055	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0048	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0055	mg
			Supplier	Copper (Cu)	7440-50-8		2.1402	mg
Mold Compound-Black	1.97	mg		Epoxy resin	proprietary data		0.1478	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0493	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.1478	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0099	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.6154	mg
Plating	0.13	mg	Supplier	Tin (Sn)	7440-31-5		0.13	mg
Wire Bond - Cu	0.07	mg	Supplier	Copper (Cu)	7440-50-8		0.07	mg